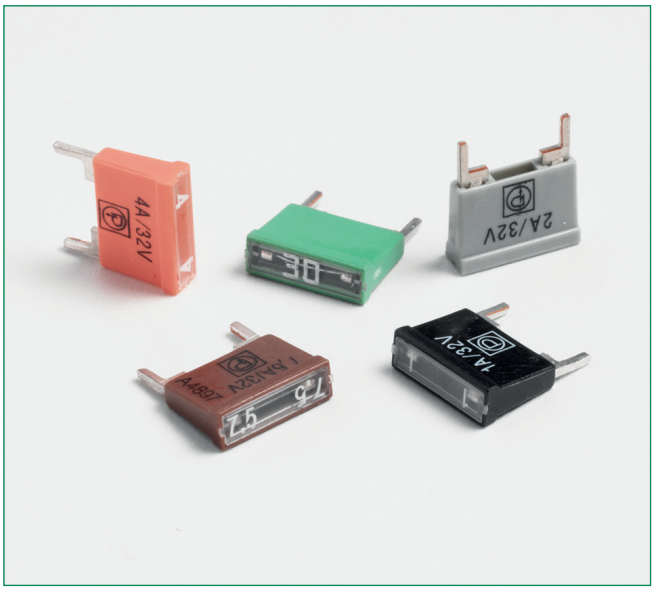
FP1 MINI® STYLE PCB FUSE RATED 32V



Specifications

Insulating body:	Out of thermoplastic (UL 94-V0, heat-resistant)
Cover:	Out of thermoplastic (V0, transparent), Visible melting-element Shunt: Red, not transparent
Terminals:	Soldering pins Copper alloy, gal. Sn plated
Interrupting Rating:	1000 A @ 32 VDC
Complies with:	UL 248 Special Purpose Fuses
cULus Recognized:	File No. E10480

Ordering Information

Part Number	Package Size
168.6585.xxx2	1500
168.6585.xxx6	100

Description

The FP1 is a MINI® style fuse for direct through-hole pcb soldering. For wave solder application the use of LF 0874 wave solder profile (see next page) is recommended. The FP1 has similar performance characteristics as the standard FK1 fuse.

Time-Current Characteristics

% of Rating	Opening Time Min / Max (s)
110	360,000 s / –
135	0.750 s / 1,800 s
200	0.150 s / 5 s
350	0.040 s / 0.500 s
600	0.020 s / 0.100 s

Ratings

Part Number	Current Rating	Housing Color	Typ. Voltage Drop Littelfuse max.	Cold Resistance	I^2t
168.6585.410_	1A		135 mV	100 mΩ	0.83 A^2s
168.6585.420_	2A		110 mV	43.0 mΩ	3.31 A^2s
168.6585.430_	3A		110 mV	27.0 mΩ	7.45 A^2s
168.6585.440_	4A		110 mV	21.3 mΩ	16.7 A^2s
168.6585.450_	5A		105 mV	16.2 mΩ	19.8 A^2s
168.6585.475_	7.5A		100 mV	9.70 mΩ	44.5 A^2s
168.6585.510_	10A		110 mV	7.40 mΩ	79.2 A^2s
168.6585.515_	15A		105 mV	4.50 mΩ	178 A^2s
168.6585.520_	20A*		100 mV	3.10 mΩ	331 A^2s
168.6585.525_	25A*		105 mV	2.60 mΩ	653 A^2s
168.6585.530_	30A*		105 mV	1.90 mΩ	1,264 A^2s
160.6585.0002	Shunt*		60 mV	1.35 mΩ	1,800 A^2s

*No UL Certification Available

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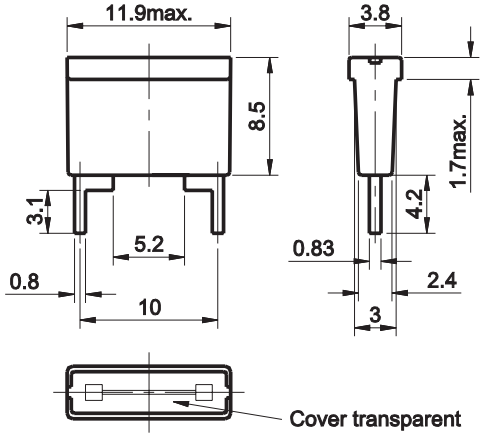
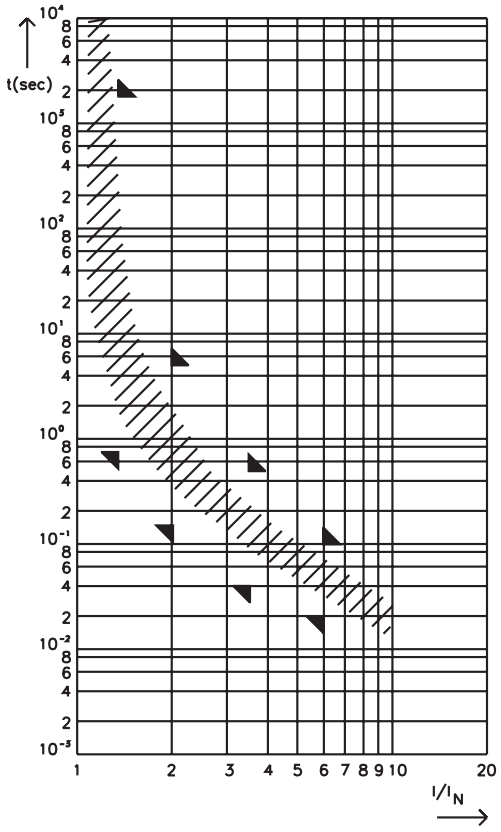
Dimensions

Dimensions in mm

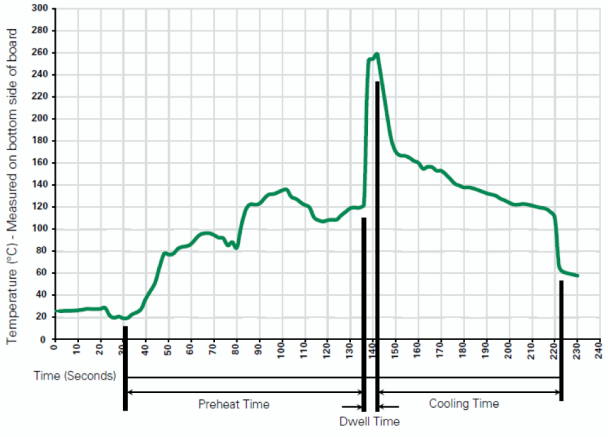


Pre-Arcing Time-Limits



FI = 1.33 (max. operating current: 0.75 x I_{rat} at 23°C)

Soldering Parameters - Wave Soldering



Recommended Process Parameters:

Wave Parameter	Lead-Free Recommendation
Preheat: (Depends on Flux Activation Temperature)	(Typical Industry Recommendation)
Temperature Minimum:	100° C
Temperature Maximum:	150° C
Preheat Time:	60-180 seconds
Solder Pot Temperature:	260° C Maximum
Solder Dwell Time:	2-5 seconds

Recommended Hand-Solder Parameters:

Solder Iron Temperature: 350° C +/- 5°C
Heating Time: 5 seconds max.

Note: These devices are not recommended for IR or Convection Reflow process.